

ABSTRACT

Compositions and methods are provided whereby electronic components may be produced that comprise a) a substrate layer; b) an insulator layer coupled to the substrate layer, wherein the insulator layer comprises at least two different kinds of embedded passive components; and c) at least one additional layer coupled to the insulator layer. A preferred method comprises a) imaging an insulator layer to create a first pattern on the insulator layer; b) etching the first pattern on the insulator layer to create a first compartment in the insulator layer; c) filling the first compartment with a first material to form a first passive component; d) imaging the insulator layer to create a second pattern on the insulator layer; e) etching the second pattern on the insulator layer to create a second compartment in the insulator layer; and f) filling the second compartment with a second material to form a second passive component.

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